



N- and P-Channel 30 V (D-S) MOSFET



Marking code: RI

PRODUCT SUMMARY							
	N-CHANNEL	P-CHANNEL					
V _{DS} (V)	30	-30					
$R_{DS(on)}(\Omega)$ at $V_{GS} = \pm 10 \text{ V}$	0.388	1.070					
$R_{DS(on)}$ (Ω) at $V_{GS} = \pm 4.5 \text{ V}$	0.525	2.590					
Q _g typ. (nC)	0.55	0.8					
I _D (A) ^a	0.7	-0.46					
Configuration	Dual						

FEATURES

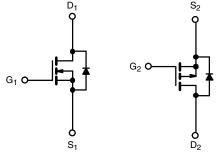
- TrenchFET® power MOSFET
- 100 % R_g tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC converter
- · Load switch



N-Channel MOSFET

P-Channel MOSFET

ORDERING INFORMATION				
Package	SOT-363			
Lead (Pb)-free and halogen-free	Si1539DDL-T1-GE3			

ABSOLUTE MAXIMUM RATINGS	$\Gamma_A = 25 ^{\circ}\text{C}$, unles	s otherwise	e noted)		
PARAMETER		SYMBOL	N-CHANNEL	P-CHANNEL	UNIT
Drain-source voltage		V_{DS}	30	-30	V
Gate-source voltage		V_{GS}	± 20	± 20	v
	T _C = 25 °C		0.7	-0.46	
Continuous drain surrent (T = 150 °C)	T _C = 70 °C] , [0.6	-0.36	
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	l _D	0.7 b, c	-0.42 b, c	
	T _A = 70 °C		0.5 b, c	-0.33 b, c	Α
	T _C = 25 °C	Is	0.3	-0.3	
Source-drain current diode current	T _A = 25 °C		0.2 b, c	-0.2 b, c	
Pulsed drain current (t = 100 μs)		I _{DM}	2	-1	
Maximum power dissipation	T _C = 25 °C		0.34	0.34	
	T _C = 70 °C		0.22	0.22	w
	T _A = 25 °C	P_{D}	0.29 b, c	0.29 b, c	VV
	T _A = 70 °C	1	0.18 b, c	0.18 b, c	1
Operating junction and storage temperature range		T _J , T _{stg}	-55 to	°C	

THERMAL RESISTANCE RATINGS							
PARAMETER		SYMBOL	N-CHANNEL		P-CHANNEL		
PANAMETER		STIVIBUL	TYP.	MAX.	TYP.	MAX.	UNIT
Maximum junction-to-ambient b, d	t ≤ 10 s	R_{thJA}	365	438	365	438	°C/W
Maximum junction-to-foot (drain)	Steady state	R_{thJF}	308	370	308	370	5

Notes

- a. Based on T_C = 25 °C
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. Maximum under steady state conditions is 486 °C/W (N-Channel) and 486 °C/W (P-Channel)



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP. a	MAX.	UNIT
Static	OTHIBOL	1201 CONDITIONS		IVIIIV.		WAX.	Oltin
otatio		V _{GS} = 0 V, I _D = 250 μA	N-Ch	30	_	_	
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	P-Ch	-30	-	-	V
		I _D = 250 μA	N-Ch	-	30	-	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = -250 μA	P-Ch	-	-25	-	
		I _D = 250 μA	N-Ch	-	-3.6	-	mV/°(
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	P-Ch	1	3.1	-	1
	1,,	$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	1.2	-	2.5	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	-1.5	-	-3	V
			N-Ch	-	-	± 100	
Gate-body leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	P-Ch	-	-	± 100	nA
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch	-	-	1	μΑ
_		V _{DS} = -30 V, V _{GS} = 0 V	P-Ch	ı	-	-1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	N-Ch	-	-	10	
		V _{DS} = -30 V, V _{GS} = 0 V, T _J = 55 °C	P-Ch	-	-	-10	
		V _{DS} = 5 V, V _{GS} = 10 V	N-Ch	2	-	-	<u> </u>
On-state drain current b	I _{D(on)}	V _{DS} = -5 V, V _{GS} = -10 V	P-Ch	-1	-	-	A
		V _{GS} = 10 V, I _D = 0.6 A	N-Ch	-	0.323	0.388	Ω
		V _{GS} = -10 V, I _D = -0.4 A	P-Ch	-	0.890	1.070	
Drain-source on-state resistance b	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 0.1A	N-Ch	-	0.437	0.525	
	20(0.1)	V _{GS} = -5 V, I _D = -0.1 A		-	1.850	2.590	
		V _{GS} = -4.35 V, I _D = -0.1 A	P-Ch	ı	2.800	-	
		V _{DS} = 15 V, I _D = 0.6 A	N-Ch	-	1.2	-	
Forward transconductance b	9fs	$V_{DS} = -15 \text{ V}, I_{D} = -0.4 \text{ A}$	P-Ch	-	0.6	-	S
Dynamic ^a							
			N-Ch	-	28	-	
Input capacitance	C _{iss}	N-Channel	P-Ch	-	21	-	
		$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch	=	10	-	pF
Output capacitance	C _{oss}	P-Channel	P-Ch	1	10	-	
Reverse transfer capacitance C _{rss}		$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch	-	5	-	
	G _{rss}		P-Ch	-	6	-	
		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 0.6 A	N-Ch	-	1	1.5	nC
Total gate charge Gate-source charge		$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -0.4 \text{ A}$	P-Ch	-	1.5	3	
	Qg		N-Ch	-	0.55	1.1	
		$\begin{aligned} &\text{N-Channel}\\ &\text{V}_{DS} = \text{15 V}, \text{V}_{GS} = \text{4.5 V} \text{I}_{D} = \text{0.6 A} \end{aligned}$	P-Ch	-	0.8	1.2	
	Q _{gs}		N-Ch	-	0.2	-	
		P-Channel	P-Ch	-	0.4	-	
	_	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.4 \text{ A}$	N-Ch	-	0.2	-	1
Gate-drain charge	Q _{gd}		P-Ch	-	0.35	-	1
Gate resistance	<u> </u>	, ,	N-Ch	0.7	3.7	7.4	Ω
	R_g	f = 1 MHz	P-Ch	0.3	15	30	



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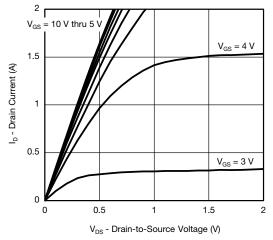
SPECIFICATIONS (T _J = 25 °C		,					
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP. a	MAX.	UNIT	
Dynamic ^a			ı		T		ı
Turn-on delay time	t _{d(on)}		N-Ch	-	2	4	
<u> </u>	u(on)	N-Channel	P-Ch	-	4	8	
Rise time	t _r	$V_{DD} = 15 \text{ V}, R_L = 30 \Omega$	N-Ch	-	14	21	
	•	$I_D \cong 0.5 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	P-Ch	-	18	30	
Turn-off delay time	t _{d(off)}	P-Channel V_{DD} = -15 V, R_L = 38 Ω	N-Ch	-	11	20	
<u> </u>	u(on)	$V_{DD} = -13 \text{ V, } R_L = 36 \Omega$ $I_D \cong -0.4 \text{ A, } V_{GEN} = -10 \text{ V, } R_g = 1 \Omega$	P-Ch	-	8	16	
Fall time	t _f		N-Ch	-	9	18	ns
	'		P-Ch	-	18	30	
Turn-on delay time	t _{d(on)}		N-Ch	-	26	39	
	-4(01)	N-Channel	P-Ch	-	22	33	
Rise time	t _r	$V_{DD} = 15 \text{ V}, R_L = 30 \Omega$	N-Ch	-	25	38	
	er .	$I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	P-Ch	-	28	42	
Turn-off delay time	t _{d(off)}	$\begin{array}{c} \text{P-Channel} \\ \text{V}_{DD} = \text{-15 V, R}_L = 50 \ \Omega \\ \text{I}_D \cong \text{-0.3 A, V}_{GEN} = \text{-4.5 V, R}_g = 1 \ \Omega \end{array}$	N-Ch	-	14	21	
			P-Ch	-	4	8	
Fall Time	t _f		N-Ch	-	15	23	
Tan Time	ч		P-Ch	-	18	30	
Drain-Source Body Diode Characteris	stics						
Continuous source-drain diode current	Is	T _C = 25 °C	N-Ch	-	-	0.3	
Continuous source-drain diode current	Į9	16 - 23 0	P-Ch	-	-	-0.3	Α
Pulse diode forward current	Levi		N-Ch	-	-	2	
$(t = 100 \ \mu s)$	I _{SM}		P-Ch	-	-	-1	
Body diode voltage	V_{SD}	I _S = 0.5 A	N-Ch	-	0.8	1.2	V
body diode voltage	VSD	I _S = -0.4 A	P-Ch	-	-0.8	-1.2	V
Dody diada rayara ragayan tima	t _{rr}		N-Ch	-	10	20	
Body diode reverse recovery time			P-Ch	-	13	20	ns
Body diode reverse recovery charge C	Q _{rr}	N-Channel $I_F=0.5$ A, di/dt = 100 A/µs, $T_J=25\ ^{\circ}C$	N-Ch	-	3	6	0
			P-Ch	-	8	16	nC
Daviera recovery fell time		- 0 5 A di/dt - 100 A/us T - 25 °C	N-Ch	-	6	-	
Reverse recovery fall time	t _a		P-Ch	-	7	-	
D		1	N-Ch	-	4	-	ns
Reverse recovery rise time	t _b		P-Ch	-	6	-	

Notes

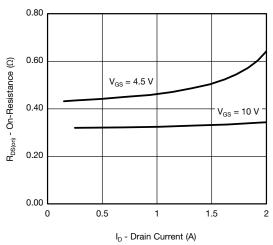
- a. Guaranteed by design, not subject to production testing
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

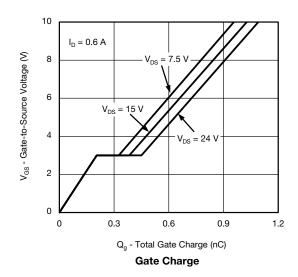


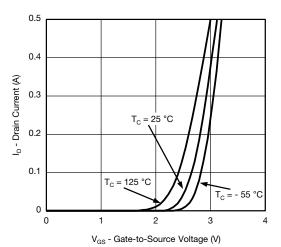


Output Characteristics

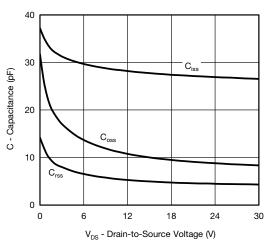


On-Resistance vs. Drain Current and Gate Voltage

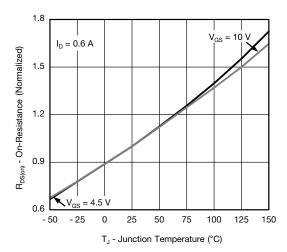




Transfer Characteristics

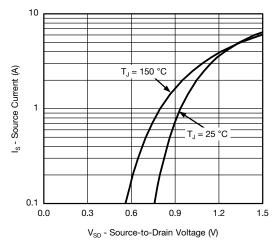


Capacitance

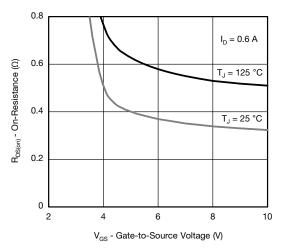


On-Resistance vs. Junction Temperature

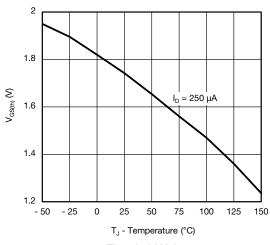




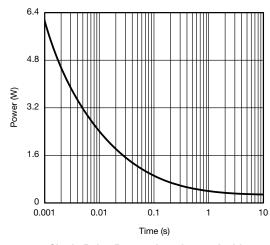
Source-Drain Diode Forward Voltage



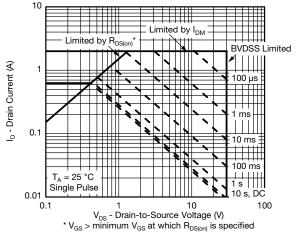
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

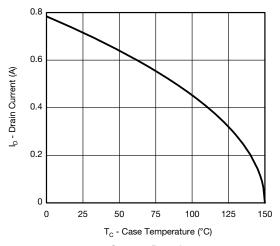


Single Pulse Power, Junction-to-Ambient

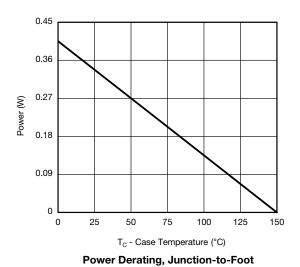


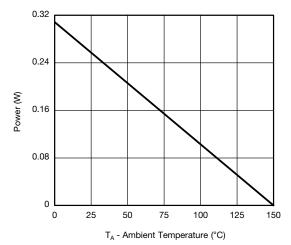
Safe Operating Area, Junction-to-Ambient





Current Derating a



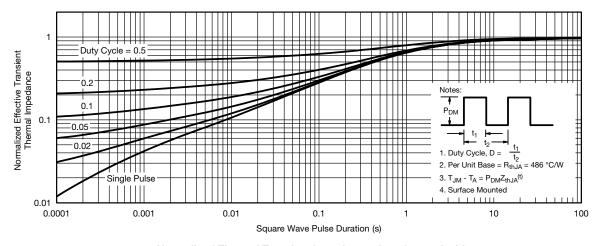


Power Derating, Junction-to-Ambient

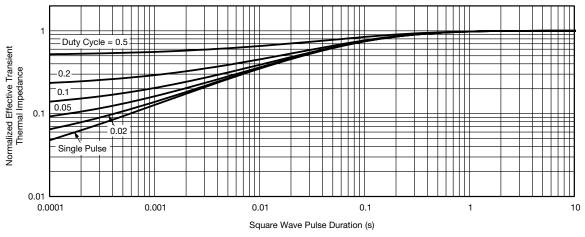
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



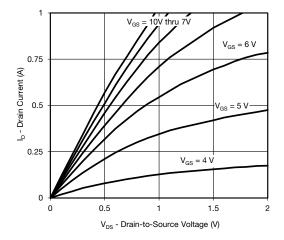


Normalized Thermal Transient Impedance, Junction-to-Ambient

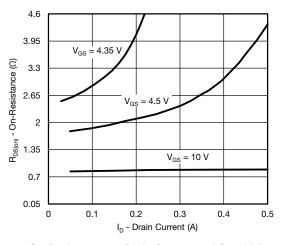


Normalized Thermal Transient Impedance, Junction-to-Foot

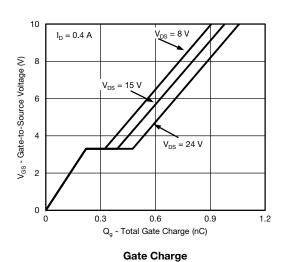


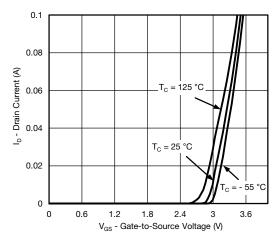


Output Characteristics

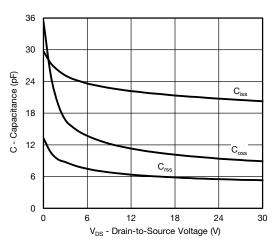


On-Resistance vs. Drain Current and Gate Voltage

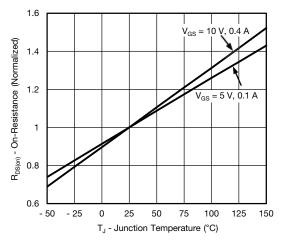




Transfer Characteristics

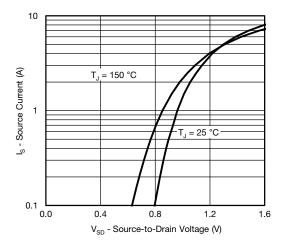


Capacitance

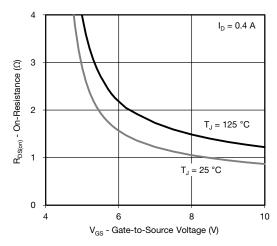


On-Resistance vs. Junction Temperature

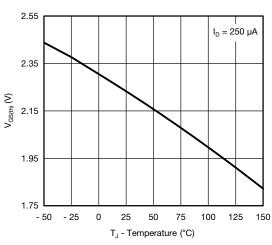




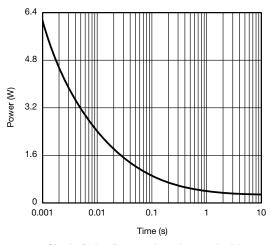
Source-Drain Diode Forward Voltage



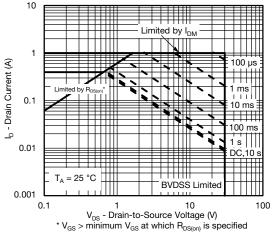
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

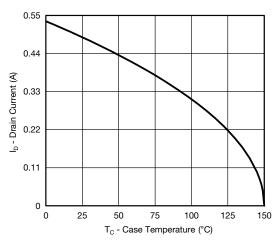


Single Pulse Power, Junction-to-Ambient

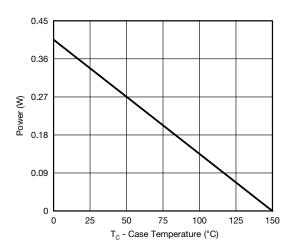


Safe Operating Area, Junction-to-Ambient

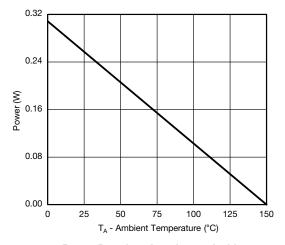




Current Derating a



Power Derating, Junction-to-Foot

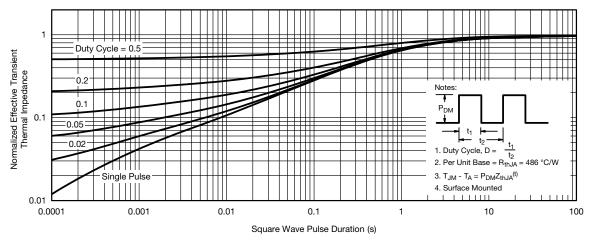


Power Derating, Junction-to-Ambient

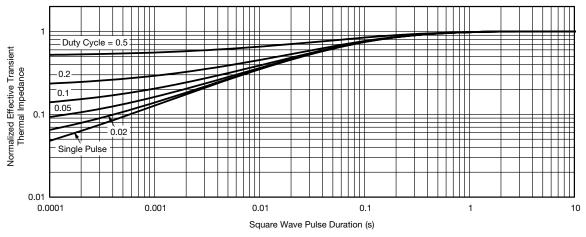
Note

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Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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